

Operation: SMT+DIP 沉板式 & 3.1Type-C 连接器/防水结构



LTEM NO.: MC-313F-14 (Consumer Electronics)
(9.65L×9.20W×4.00H & DUL SMT LOW PCB TYPE)

Universal Serial Bus Connectors



Technical parameter

外焊 SMT+DIP

PROJECT	LEVEL	A[better product]	B[average product]
		Electrical Properties Contact Rating Initial Contact Resistance Insulation Resistance Withstand Voltage There No Load Rated Load Storage temp.	3A, 24V DC 30mΩ max. 100MΩ min.500V DC 500V AC for 1 minute 6,500 Cycles 5,500 Cycles -25℃~+75℃(Operating Temp:

側向導入 LATERAL

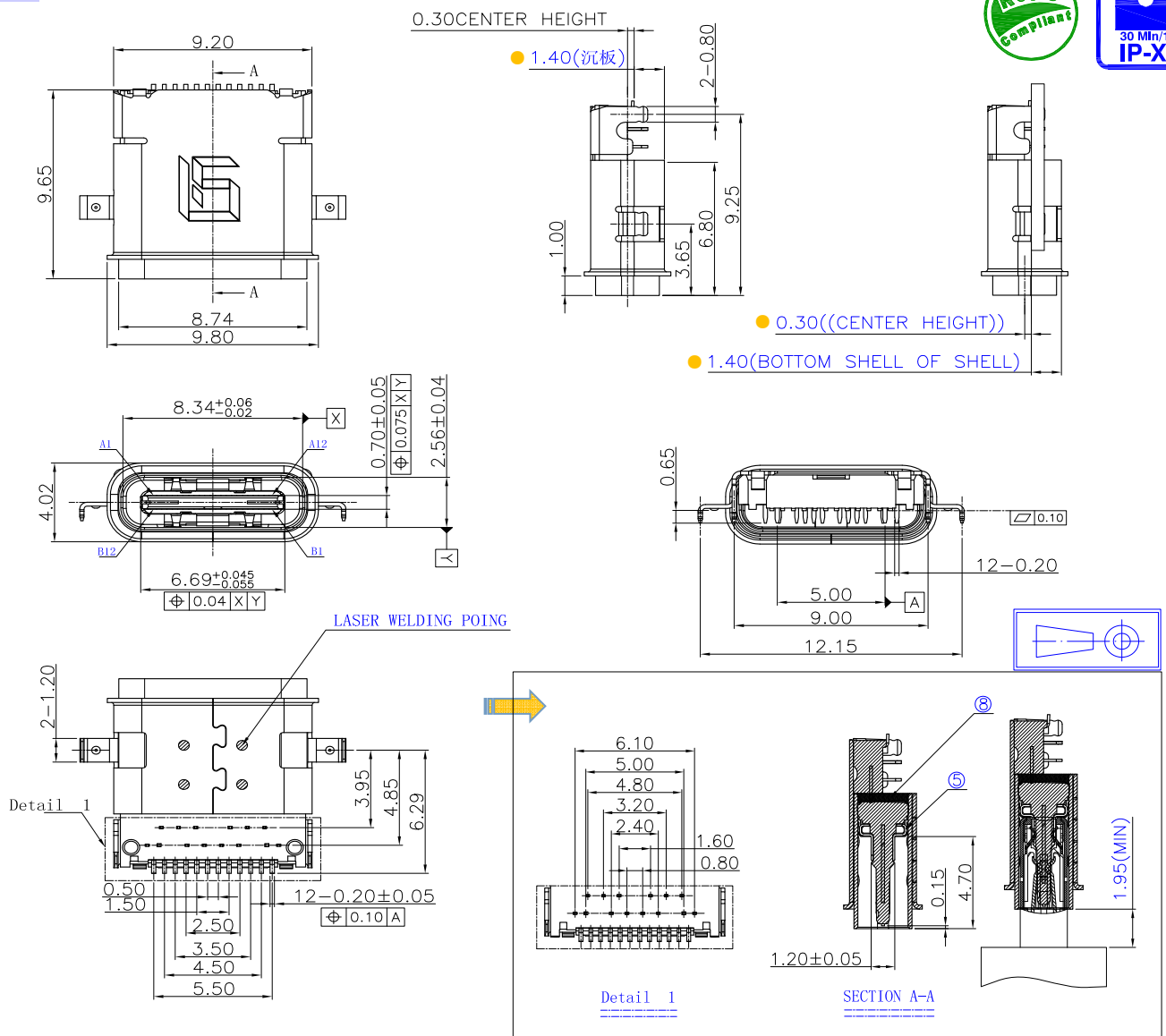
精密部品 NICETY

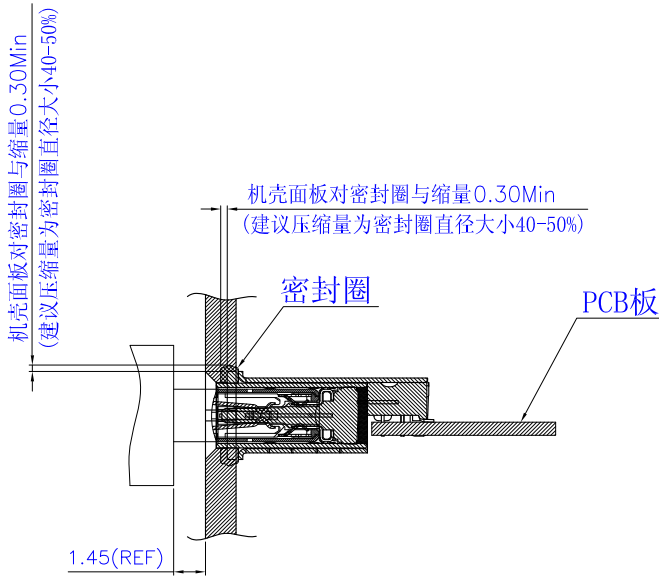
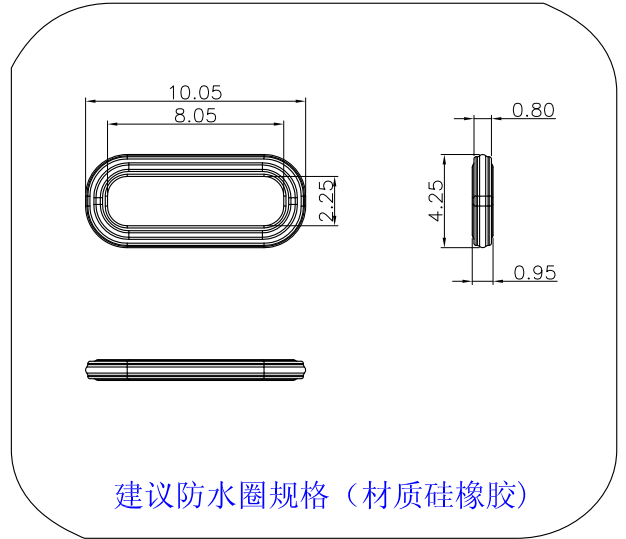
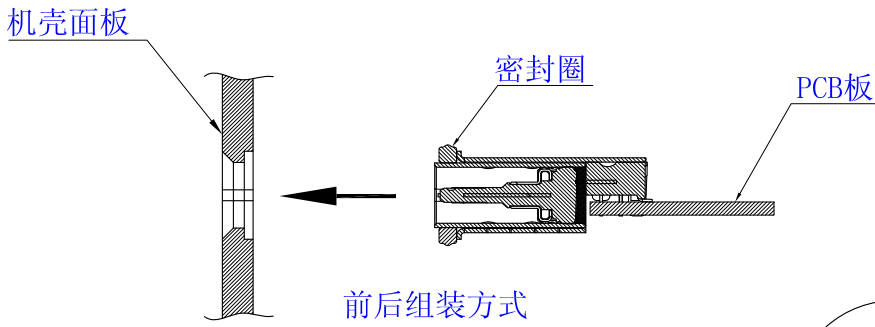
可靠 STABILIZE

環保材質 RoHS

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Unit:mm



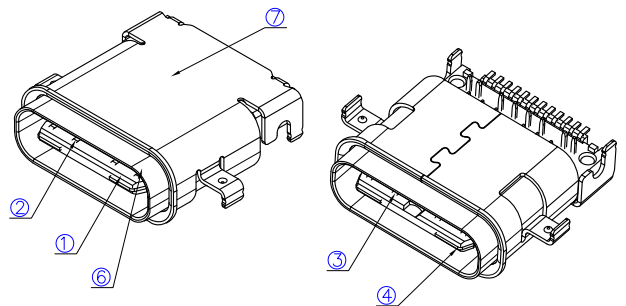


组装面板后公母头对插示意图



SPECIFIED TOLERANCES
UNLESS OTHERWISE

DECIMALS	ANGLES
X.X : ±0.25	X.X : ±3°
X.XX : ±0.15	X.XX : ±2°
X.XXX : ±0.10	



Material declaration			
No.	NAME	MATERIAL	DESCRIPTION
① A	HOUSING	-	HIGH TEMP[Black]
② B	Terminal-A 12PIN	COPPER ALLOY 【G/F】	Au:15 μ" PLATING OVERALL;[t=0.12mm]铜镍硅合金
③ C	Terminal-B 12PIN	COPPER ALLOY 【G/F】	Au:15 μ" PLATING OVERALL;[t=0.12mm]铜镍硅合金
④ D	MID PLATE	STAINLESS 【G/F】	STAINLESS STEEL(t=0.15mm)
⑤ E	GND PLATE	STAINLESS 【G/F】	STAINLESS STEEL/ Ni PLATING(t=0.10mm)
⑥ F	SHELL-#1	STAINLESS 【G/F】	STAINLESS STEEL/ Ni PLATING(t=0.20mm)
⑦ G	SHELL-#2	STAINLESS 【G/F】	STAINLESS STEEL/ Ni PLATING(t=0.20mm)
⑧ H	GLUE WATER	-	EPOXY[Black]

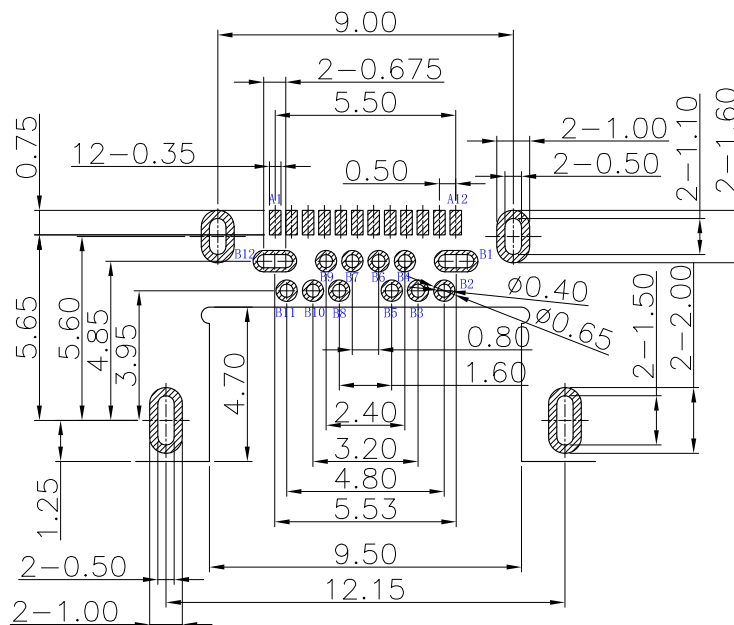
Operating Force

Inward
Exiting

5.0~8.0N. (1N.=100gram-force)
5.0~8.0N. (1N.=100gram-force)

Solder-ability (Max.)

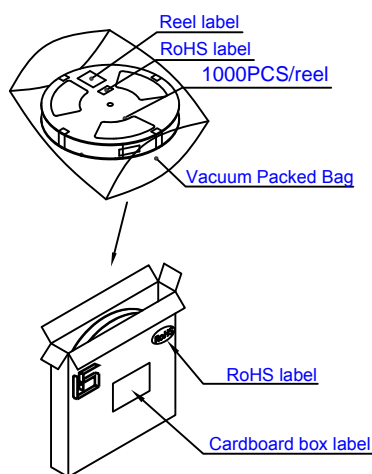
IR Reflow:255°C, 5sec. Manual :350°C, 3sec.



Tolerance:±0.05,Thickness=0.60mm

PIN ASSIGNMENTS

PIN	Signal NAME	Description	PIN	Signal NAME	Description
A 1	GND	Ground return	B12	GND	Ground return
A 2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of second SuperSpeed RX differential pair
A 3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of second SuperSpeed RX differential pair
A 4	V BUS	Bus Power	B 9	V BUS	Bus Power
A 5	CC1	Configuration Channel	B 8	SBU2	Sideband Use (SBU)
A 6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B 7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A 7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B 6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A 8	SBU1	Sideband Use (SBU)	B 5	CC2	Configuration Channel
A 9	V BUS	Bus Power	B 4	V BUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B 3	SSTXn2	Negative half of first SuperSpeed TX differential pair2
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B 2	SSTXp2	Positive half of first SuperSpeed TX differential pair2
A12	GND	Ground return	B 1	GND	Ground return



注記 NOTICE

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自动浸焊时

項目	條件
助焊剂附着量	不附着于零部件貼裝面的程度
预热温度	印刷电路板焊接面的周围温度 100°C max.
预热温度时间	60s max.
焊接温度	260°C max.
焊接浸渍时间	5s max.
焊接次数	2次以下